



**Silicon Motion, Inc.**

## **SM32X Test Program and ISP Release Note**

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**SM3257 Test Program and ISP Release Note:**

Release Date	ISP Version	ISP Check Sum	Test AP Version	Description
2010/06/07	SM3257AA 2010-06-07	SM3257AAISP 0x005ABF6E	V2.03.28 V5 10/06/07 build	1. SM3257AAISP support Samsung 32nm TLC bucket00 flash K9ABG08U0A, K9BCG08U1A and K9CDG08U5A
	SM3257AA 2010-06-07	SM3257AAISP-bucket01 0x005A981D		2. SM3257AAISP support Samsung 27nm MLC K9GBG08U0A
				3. SM3257AAISP-bucket01 support Samsung 32nm TLC bucket01 flash K9ABG08U0A, K9BCG08U1A and K9CDG08U5A.
2010/07/02	SM3257AA 2010-07-02	SM3257AAISP 0x005D3C3E	V2.03.29 V3 10/07/02 build	1. SM3257AAISP support Samsung 32nm MLC
		SM3257AAISP-bucket01 0x005D12F0		2. SM3257AAISP support Intel/Micron L74A
				3. SM3257AAISP support Intel/Micron L73A
				4. SM3257AAISP enhance suddenly power cycling protection
				5. SM3257AAISP-bucket01 enhance suddenly power cycling protection
				6. SM3257AAISP support Hynix 26nm MLC.
				7. MP tool fixed device disconnection issue when MP tool initial card.
2010/08/18	SM3257AA 2010-08-09	SM3257AAISP 0x005D3AEF	V2.03.31 V1 10/08/18 build	1. SM3257AAISP, SM3257AAISP-bucket01 and SM3257AAISP-HY32 fixed power cycling issue to cause system block occurs ECC fail.
	SM3257AA 2010-08-16	SM3257AAISP-bucket01 0x005D9003		2. SM3257AAISP, SM3257AAISP-bucket01 and SM3257AAISP-HY32 fixed build link block issue when plug in UFD.
	SM3257AA 2010-08-09	SM3257AAISP-HY32 0x005D8449		3. SM3257AAISP support Hynix 26nm MLC H27UCG8T2MYR.
				4. SM3257AAISP-HY32 support Hynix 32nm TLC H27UBG8M2A.



				<ol style="list-style-type: none"> <li>MP tool fixed update ISO issue (CDROM + Public mode change to Public only mode without do-pretest) .</li> <li>MP tool add QC function which check capacity and used space.</li> <li>MP tool add Multiple Erase all function.</li> </ol>
2010/09/23	SM3257AA	SM3257AAISP.bin	V 2.03.31 v13	<ol style="list-style-type: none"> <li>SM3257AAISP fixed Cache read and 2Plane Read to cause burn in fail without mark bad block for Hynix 26nm MLC H27UCG8T2MYR supporting.</li> <li>SM3257AAISP adjust clock rate from 60MHz to 48MHz for Hynix 32nm MLC 16Gbit H27UAG8T2BTR supporting.</li> <li>SM3257AAISP-HY32 fixed 2Plane Read cause burn-in fail issue for Hynix 32nm TLC HY27UBG8M2A.</li> <li>SM3257AAISP-bucket01 fixed Samsung framework, Getstatus, setfeature and clearfeature do endpoint halt for EP0.</li> <li>SM3257AAISP support Micron L74A new flash ID (2C 88 24 49)</li> <li>SM3257AAISP support Micron L72A MT29F16G08CBACA</li> <li>SM3257AAISP support new Led function when MP tool initialization</li> <li>SM3257AAISP support Micron L73A MT29F32G08CBACA with 1CE2Die bonding.</li> <li>MP tool support LED blinking when initial UFD device.</li> </ol>
	2010-09-22	0x005E3C38	10/09/08	
	SM3257AA	SM3257AAISP-bucket01.bin		
	2010-09-14	0x005E5DAA		
	SM3257AA	SM3257AAISP-HY32.bin		
	2010-09-22	0x005E24B3		
2010/09/23	SM3257AA	SM3257AAISP.bin	V 2.03.32 v12	<ol style="list-style-type: none"> <li>SM3257AAISP support Micron L72A MT29F16G08CBACA.</li> <li>SM3257AAISP support Intel L72A 29F16G083AME1.</li> </ol>
	2010-09-22	0x005E3C38	10/10/15	



	SM3257AA 2010-09-14 SM3257AA 2010-09-22	SM3257AAISP-bucket01.bin 0x005E5DAA SM3257AAISP-HY32.bin 0x005E24B3		<ol style="list-style-type: none"> <li>SM3257AAISP support Samsung 42nm SLC K9F8G08U0A.</li> <li>SM3257AAISP support Samsung 51nm MLC K9LBG08U0M.</li> <li>SM3257AAISP support Intel L74A new flash ID (89 88 24 CB) with 1CE2Die bonding.</li> <li>SM3257AAISP support Micron 34nm SLC MT29F32G08AFABA</li> <li>MP tool add FDD only function supporting</li> <li>MP tool Fixed MAC OS dismount device issue</li> <li>MP tool add QC function check disk label with all eleven characters.</li> </ol>
2010/11/03	SM3257AA 2010-11-02 SM3257AA 2010-11-02 SM3257AA 2010-11-02	SM3257AAISP.bin 0x005EAD3A SM3257AAISP-bucket01.bin 0x005F0CDF SM3257AAISP-HY32.bin 0x005E9347	V 2.03.33 v1 10/11/02	<ol style="list-style-type: none"> <li>SM3257AAISP support Hynix 32nm MLC H27UEG8YEA and H27UDG8V5A.</li> <li>SM3257AAISP fixed four die build link table issue when suddenly power cycling testing.</li> <li>MP tool fixed serial number issue with production date update.</li> <li>MP tool fixed show much bad block issue with non-initial card.</li> <li>MP tool fixed QC format issue.</li> <li>MP tool fixed QC check used space issue.</li> </ol>
2010/11/22	SM3257AA 2010-11-18 SM3257AA 2010-11-02 SM3257AA 2010-11-18	SM3257AAISP.bin 0x005E9C5F SM3257AAISP-bucket01.bin 0x005F0CDF SM3257AAISP-HY32.bin 0x005E8599	V 2.03.34v12 10/11/22	<ol style="list-style-type: none"> <li>SM3257AAISP support Intel L73A JS29F32G08AAME1 1CE2Die bonding (Flash ID: 89 88 05 CA)</li> <li>SM3257AAISP support Samsung 27nm MLC K9HDG08U1A</li> <li>SM3257AAISP support Intel L72A 29F16G08AAME1.</li> <li>SM3257AAISP support Samsung 42nm MLC K9PDG08U5D 16GB ULGA.</li> </ol>



				<ol style="list-style-type: none"> <li>SM3257AAISP fixed Hynix 32nm MLC, 26nm MLC and 32nm TLC write performance faster than read performance when WINSAT testing.</li> <li>MP tool add function reset hub with auto-handle.</li> <li>MP tool fixed QC check disk label issue with FAT32.</li> </ol>
2010/12/10	SM3257AA 2010-12-01 SM3257AA 2010-12-01 SM3257AA 2010-12-01	SM3257AAISP.bin 0x005EAADB SM3257AAISP-bucket01.bin 0x005F0B7F SM3257AAISP-HY32.bin 0x005E91E7	V 2.03.35 v4 10/12/07	<ol style="list-style-type: none"> <li>SM3257AAISP support Samsung 27nm MLC K9HGD08U1A</li> <li>SM3257AAISP fixed enable watch dog cause USB disconnection issue when high-low temperature swing test</li> <li>SM3257AAISP support Toshiba 24nm MLC TC58NVG6D2GTA00.</li> <li>SM3257AAISP support SanDisk 24nm MLC SDTNOQAHHER - 008G</li> <li>SM3257AAISP support Samsung 32nm MLC K9HCG08U2E</li> <li>SM3257AAISP fixed enable Cache Read and Two Plane Read Cause “占容量” issue for Samsung 27nm MLC K9GBG08U0A supporting.</li> <li>MP tool fixed QC function without erase issue for ISP verifies.</li> <li>MP tool fixed Auto handler with Ethernet function issue.</li> </ol>
2011/01/06	SM3257AA 2010-12-30 SM3257AA 2010-12-30 SM3257AA	SM3257AAISP.bin 0x005EE61C SM3257AAISP-bucket01.bin 0x005F43D6 SM3257AAISP-HY32.bin	V 2.03.36 v1 11/01/06	<ol style="list-style-type: none"> <li>SM3257AAISP modify cross die function process to fixed Samsung 35nm MLC K9PFG08U5M burn in issue.</li> <li>SM3257AAISP add check VDT before build link table to fixed occupied capacity of UFD issue.</li> <li>SM3257AAISP support Hynix 26nm MLC HY27UBG8T2BTR.</li> </ol>



	2010-12-30	0x005EC37B		<ul style="list-style-type: none"><li>4. MP tool add QC debug option.</li><li>5. MP tool support Static Size function.</li></ul>
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